2SD1480

Silicon NPN triple diffusion planar type

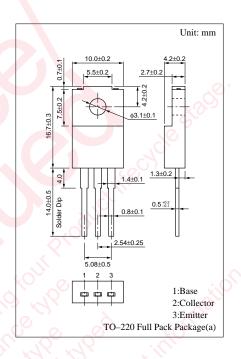
For power amplification Complementary to 2SB1052

Features

- High forward current transfer ratio h_{FE} which has satisfactory linearity
- ullet Low collector to emitter saturation voltage $V_{\text{CE(sat)}}$
- Full-pack package which can be installed to the heat sink with one screw

Absolute Maximum Ratings (T_C=25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	60	V
Collector to emitter voltage	V _{CEO}	60	V
Emitter to base voltage	V _{EBO}	6	V
Peak collector current	I _{CP}	4	A
Collector current	$I_{\rm C}$	2	A
Collector power T _C =25°C	D	25	777.10
dissipation Ta=25°C	$P_{\rm C}$	2	W
Junction temperature	Tj	150	G°C . o
Storage temperature	T _{stg}	-55 to +150	°C (



Electrical Characteristics (T_C=25°C)

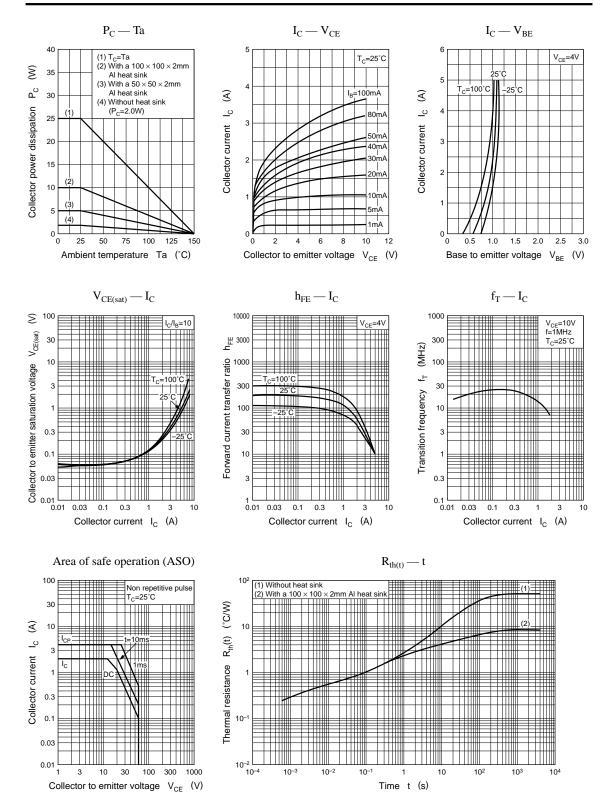
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I _{CES}	$V_{CE} = 60V, V_{BE} = 0$			200	μА
	I_{CEO}	$V_{CE} = 30V, I_B = 0$	S		300	μА
Emitter cutoff current	I_{EBO}	$V_{EB} = 6V, I_C = 0$			1	mA
Collector to emitter voltage	V_{CEO}	$I_C = 30 \text{mA}, I_B = 0$	60			V
Forward current transfer ratio	h _{FE1}	$V_{CE} = 4V, I_{C} = 0.1A$	35			
	h _{FE2} *	$V_{CE} = 4V, I_C = 1A$	70		250	
Base to emitter voltage	V_{BE}	$V_{CE} = 4V, I_C = 1A$			1.2	V
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 2A, I_B = 0.2A$			2	V
Transition frequency	f_T	$V_{CE} = 10V, I_{C} = 0.5A, f = 1MHz$		20		MHz
Turn-on time	t _{on}	1 14 1 014 1 014		0.2		μs
Storage time	t _{stg}	$I_C = 1A, I_{B1} = 0.1A, I_{B2} = -0.1A,$		3.5		μs
Fall time	t _f	$V_{CC} = 50V$		0.7		μs

*h_{FE2} Rank classification

Rank	Q	P		
h_{FE2}	70 to 150	120 to 250		

Panasonic 1

Power Transistors 2SD1480



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